

ABSTRACT

PHENOLIC RESIN MOLDING MATERIAL

The present invention provides a phenolic resin molding material high in flowability and heat stability in the molten state and excellent in curability at high temperatures which contains (a) a high ortho-novolak type phenolic resin having a number-average molecular weight of 350-500 and an ortho-bond/para-bond ratio of 1.5-2.5, (b) hexamethylene-tetramine, (c) a low-molecular polyolefin compound and (d) a filler. This phenolic resin molding material can further contain a crystalline phenolic compound having two or more benzene rings and/or a monohydric aliphatic alcohol to further improve the flowability, heat stability and curability.